



Alpha Assembly Solutions
8/F., Paul Y. Centre, 51 Hung To Road
Kwun Tong, Kowloon, Hong Kong

Sally Lee
Regional Marketing Communications Manager - AP
O +852 3190.3100
F +852 2347.5301
SallyLee@alphaassembly.com
AlphaAssembly.com

FOR IMMEDIATE RELEASE

Contact: Sally Lee
SallyLee@AlphaAssembly.com

Alpha to Showcase Latest Products for Die Attach and SMT Assembly Solutions at Internecon Japan 2018

Somerset, NJ – December 14th, 2017 – Alpha Assembly Solutions, the world leader in the production of electronic soldering materials and bonding materials, will be exhibiting its latest range of product solutions, alongside its sister company MacDermid Enthone Electronics Solutions, at the 2018 Internecon Japan show to be held in Tokyo from January 17th – 19th, 2018.

At the show, Alpha, a part of the MacDermid Performance Solutions group of business, will be exhibiting its latest range of products for SMT Assembly Solutions, Die Attach Assembly Solutions and Industrial Assembly Solutions. The products include Agromax®, Atrox®, High Temperature Dipping Alloys, Low Melting Point Solder Paste, Assembly Polymers, Innolot Alloys, PowerBond and AccuFlux.

In addition, Alpha will showcase its newly developed solution for void reduction under bottom terminated components (BTC), the ALPHA® AccuFlux™ BTC-578 Preform System. The system combines ALPHA® AccuFlux™ BTC-578 Preform, solder paste, engineered stencil designs and optimized processing parameters to dramatically and consistently decrease voiding.

For more information on Alpha's latest product technologies, visit Alpha Assembly Solutions Booth at Internecon Japan **Hall East 5-4**.

About 47th Internecon Japan

Internecon Japan is the world's leading SMT exhibition gathering Equipment, Solutions and Services for Electronics Manufacturing. For more information, visit www.nepconjapan.jp/en/Home/

Date: Wednesday 17th – Friday 19th January 2018 (10:00-18:00, Last Day until 17:00)
Venue: Tokyo Big Sight, Japan

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About Alpha Assembly Solutions

Alpha Assembly Solutions, a MacDermid Performance Solutions Business, is the global leader in the development, manufacturing and sales of innovative specialty materials used in a wide range of industry segments, including electronics assembly, power electronics, die attach, LED lighting, photovoltaics, semiconductor packaging, automotive and others.

With a unique global presence in over 30 locations throughout the Asia Pacific, Americas and Europe regions, Alpha supplies a full line of ALPHA® electronics assembly material products, including Solder Paste, Exactalloy® Solder Preforms, Cored Solder Wire Solder, Wave Soldering Fluxes, Bar Solder Alloys, and Stencils. It offers die attach product technologies to the power electronics segment in its Argomax®, Atrox™ and Fortibond™ brands.

For the LED segment, Alpha offers its Lumet™ products covering applications from die attach to systems assembly in the LED manufacturing process. Alpha also offers product technologies for the Photovoltaic segment, including high performance liquid fluxes and solder alloys for producing standard ribbon and bus bar, as well as, solder pastes, cored wire, conductive adhesives and preforms for use in PV module assembly. Also, Alpha's Advanced Materials unit is the leader in electronic polymers and solder materials for semiconductor packaging applications.

Since its founding in 1872, Alpha has been committed to developing and manufacturing the highest quality specialty materials. For more information, visit www.AlphaAssembly.com.

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